

Global 3D IC & 2.5D IC Packaging Market 2024 by Manufacturers, Regions, Type and Application, Forecast to 2030

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Abstracts

According to our (Global Info Research) latest study, the global 3D IC & 2.5D IC Packaging market size was valued at USD 7155.3 million in 2023 and is forecast to a readjusted size of USD 20320 million by 2030 with a CAGR of 16.1% during review period.

A three-dimensional integrated circuit (3D IC) is a package with multiple layers of silicon wafers stalked together, along with electronic components using through-silicon vias (TSVs), while a 2.5-dimensional integrated circuit (2.5D IC) is a package with an active electronic components (for example, a die or a chip) stacked on an interposer through conductive bumps or TSVs.

The Global 3D IC & 2.5D IC Packaging Market is poised to grow strong during the forecast period 2017 to 2027. Some of the prominent trends that the market is witnessing include increasing demand for high-end computing, servers, and data centers, rising demand for smartphones, tablets, and gaming devices and recent technological developments in 3D IC & 2.5D IC packaging.

The Global Info Research report includes an overview of the development of the 3D IC & 2.5D IC Packaging industry chain, the market status of Automotive (3D TSV, 2.5D and 3D Wafer-Level Chip-Scale Packaging (WLCSP)), Consumer electronics (3D TSV, 2.5D and 3D Wafer-Level Chip-Scale Packaging (WLCSP)), and key enterprises in developed and developing market, and analysed the cutting-edge technology, patent, hot applications and market trends of 3D IC & 2.5D IC Packaging.

Regionally, the report analyzes the 3D IC & 2.5D IC Packaging markets in key regions.

North America and Europe are experiencing steady growth, driven by government initiatives and increasing consumer awareness. Asia-Pacific, particularly China, leads the global 3D IC & 2.5D IC Packaging market, with robust domestic demand, supportive policies, and a strong manufacturing base.

Key Features:

The report presents comprehensive understanding of the 3D IC & 2.5D IC Packaging market. It provides a holistic view of the industry, as well as detailed insights into individual components and stakeholders. The report analysis market dynamics, trends, challenges, and opportunities within the 3D IC & 2.5D IC Packaging industry.

The report involves analyzing the market at a macro level:

Market Sizing and Segmentation: Report collect data on the overall market size, including the sales quantity (K Units), revenue generated, and market share of different by Type (e.g., 3D TSV, 2.5D and 3D Wafer-Level Chip-Scale Packaging (WLCSP)).

Industry Analysis: Report analyse the broader industry trends, such as government policies and regulations, technological advancements, consumer preferences, and market dynamics. This analysis helps in understanding the key drivers and challenges influencing the 3D IC & 2.5D IC Packaging market.

Regional Analysis: The report involves examining the 3D IC & 2.5D IC Packaging market at a regional or national level. Report analyses regional factors such as government incentives, infrastructure development, economic conditions, and consumer behaviour to identify variations and opportunities within different markets.

Market Projections: Report covers the gathered data and analysis to make future projections and forecasts for the 3D IC & 2.5D IC Packaging market. This may include estimating market growth rates, predicting market demand, and identifying emerging trends.

The report also involves a more granular approach to 3D IC & 2.5D IC Packaging:

Company Analysis: Report covers individual 3D IC & 2.5D IC Packaging manufacturers, suppliers, and other relevant industry players. This analysis includes studying their financial performance, market positioning, product portfolios, partnerships, and strategies.

Consumer Analysis: Report covers data on consumer behaviour, preferences, and attitudes towards 3D IC & 2.5D IC Packaging. This may involve surveys, interviews, and analysis of consumer reviews and feedback from different by Application (Automotive, Consumer electronics).

Technology Analysis: Report covers specific technologies relevant to 3D IC & 2.5D IC Packaging. It assesses the current state, advancements, and potential future developments in 3D IC & 2.5D IC Packaging areas.

Competitive Landscape: By analyzing individual companies, suppliers, and consumers, the report presents insights into the competitive landscape of the 3D IC & 2.5D IC Packaging market. This analysis helps understand market share, competitive advantages, and potential areas for differentiation among industry players.

Market Validation: The report involves validating findings and projections through primary research, such as surveys, interviews, and focus groups.

Market Segmentation

3D IC & 2.5D IC Packaging market is split by Type and by Application. For the period 2019-2030, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value.

Market segment by Type

3D TSV

2.5D and 3D Wafer-Level Chip-Scale Packaging (WLCSP)

Market segment by Application

Automotive

Consumer electronics

Medical devices

Military & aerospace

Telecommunication

Industrial sector and smart technologies

Major players covered

Intel Corporation

Toshiba Corp

Samsung Electronics

Stmicroelectronics

Taiwan Semiconductor Manufacturing

Amkor Technology

United Microelectronics

Broadcom

ASE Group

Pure Storage

Advanced Semiconductor Engineering

JCET

TongFu Microelectronics

Market segment by region, regional analysis covers

North America (United States, Canada and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe 3D IC & 2.5D IC Packaging product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of 3D IC & 2.5D IC Packaging, with price, sales, revenue and global market share of 3D IC & 2.5D IC Packaging from 2019 to 2024.

Chapter 3, the 3D IC & 2.5D IC Packaging competitive situation, sales quantity, revenue and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the 3D IC & 2.5D IC Packaging breakdown data are shown at the regional level, to show the sales quantity, consumption value and growth by regions, from 2019 to 2030.

Chapter 5 and 6, to segment the sales by Type and application, with sales market share and growth rate by type, application, from 2019 to 2030.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value and market share for key countries in the world, from 2017 to 2023. and 3D IC & 2.5D IC Packaging market forecast, by regions, type and application, with sales and revenue, from 2025 to 2030.

Chapter 12, market dynamics, drivers, restraints, trends and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of 3D IC & 2.5D IC Packaging.

Chapter 14 and 15, to describe 3D IC & 2.5D IC Packaging sales channel, distributors, customers, research findings and conclusion.

Contents

1 MARKET OVERVIEW

- 1.1 Product Overview and Scope of 3D IC & 2.5D IC Packaging
- 1.2 Market Estimation Caveats and Base Year
- 1.3 Market Analysis by Type
 - 1.3.1 Overview: Global 3D IC & 2.5D IC Packaging Consumption Value by Type: 2019 Versus 2023 Versus 2030
 - 1.3.2 3D TSV
 - 1.3.3 2.5D and 3D Wafer-Level Chip-Scale Packaging (WLCSP)
- 1.4 Market Analysis by Application
 - 1.4.1 Overview: Global 3D IC & 2.5D IC Packaging Consumption Value by Application: 2019 Versus 2023 Versus 2030
 - 1.4.2 Automotive
 - 1.4.3 Consumer electronics
 - 1.4.4 Medical devices
 - 1.4.5 Military & aerospace
 - 1.4.6 Telecommunication
 - 1.4.7 Industrial sector and smart technologies
- 1.5 Global 3D IC & 2.5D IC Packaging Market Size & Forecast
 - 1.5.1 Global 3D IC & 2.5D IC Packaging Consumption Value (2019 & 2023 & 2030)
 - 1.5.2 Global 3D IC & 2.5D IC Packaging Sales Quantity (2019-2030)
 - 1.5.3 Global 3D IC & 2.5D IC Packaging Average Price (2019-2030)

2 MANUFACTURERS PROFILES

- 2.1 Intel Corporation
 - 2.1.1 Intel Corporation Details
 - 2.1.2 Intel Corporation Major Business
 - 2.1.3 Intel Corporation 3D IC & 2.5D IC Packaging Product and Services
 - 2.1.4 Intel Corporation 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)
 - 2.1.5 Intel Corporation Recent Developments/Updates
- 2.2 Toshiba Corp
 - 2.2.1 Toshiba Corp Details
 - 2.2.2 Toshiba Corp Major Business
 - 2.2.3 Toshiba Corp 3D IC & 2.5D IC Packaging Product and Services
 - 2.2.4 Toshiba Corp 3D IC & 2.5D IC Packaging Sales Quantity, Average Price,

Revenue, Gross Margin and Market Share (2019-2024)

2.2.5 Toshiba Corp Recent Developments/Updates

2.3 Samsung Electronics

2.3.1 Samsung Electronics Details

2.3.2 Samsung Electronics Major Business

2.3.3 Samsung Electronics 3D IC & 2.5D IC Packaging Product and Services

2.3.4 Samsung Electronics 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)

2.3.5 Samsung Electronics Recent Developments/Updates

2.4 Stmicroelectronics

2.4.1 Stmicroelectronics Details

2.4.2 Stmicroelectronics Major Business

2.4.3 Stmicroelectronics 3D IC & 2.5D IC Packaging Product and Services

2.4.4 Stmicroelectronics 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)

2.4.5 Stmicroelectronics Recent Developments/Updates

2.5 Taiwan Semiconductor Manufacturing

2.5.1 Taiwan Semiconductor Manufacturing Details

2.5.2 Taiwan Semiconductor Manufacturing Major Business

2.5.3 Taiwan Semiconductor Manufacturing 3D IC & 2.5D IC Packaging Product and Services

2.5.4 Taiwan Semiconductor Manufacturing 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)

2.5.5 Taiwan Semiconductor Manufacturing Recent Developments/Updates

2.6 Amkor Technology

2.6.1 Amkor Technology Details

2.6.2 Amkor Technology Major Business

2.6.3 Amkor Technology 3D IC & 2.5D IC Packaging Product and Services

2.6.4 Amkor Technology 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)

2.6.5 Amkor Technology Recent Developments/Updates

2.7 United Microelectronics

2.7.1 United Microelectronics Details

2.7.2 United Microelectronics Major Business

2.7.3 United Microelectronics 3D IC & 2.5D IC Packaging Product and Services

2.7.4 United Microelectronics 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)

2.7.5 United Microelectronics Recent Developments/Updates

2.8 Broadcom

- 2.8.1 Broadcom Details
- 2.8.2 Broadcom Major Business
- 2.8.3 Broadcom 3D IC & 2.5D IC Packaging Product and Services
- 2.8.4 Broadcom 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)
- 2.8.5 Broadcom Recent Developments/Updates
- 2.9 ASE Group
 - 2.9.1 ASE Group Details
 - 2.9.2 ASE Group Major Business
 - 2.9.3 ASE Group 3D IC & 2.5D IC Packaging Product and Services
 - 2.9.4 ASE Group 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)
 - 2.9.5 ASE Group Recent Developments/Updates
- 2.10 Pure Storage
 - 2.10.1 Pure Storage Details
 - 2.10.2 Pure Storage Major Business
 - 2.10.3 Pure Storage 3D IC & 2.5D IC Packaging Product and Services
 - 2.10.4 Pure Storage 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)
 - 2.10.5 Pure Storage Recent Developments/Updates
- 2.11 Advanced Semiconductor Engineering
 - 2.11.1 Advanced Semiconductor Engineering Details
 - 2.11.2 Advanced Semiconductor Engineering Major Business
 - 2.11.3 Advanced Semiconductor Engineering 3D IC & 2.5D IC Packaging Product and Services
 - 2.11.4 Advanced Semiconductor Engineering 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)
 - 2.11.5 Advanced Semiconductor Engineering Recent Developments/Updates
- 2.12 JCET
 - 2.12.1 JCET Details
 - 2.12.2 JCET Major Business
 - 2.12.3 JCET 3D IC & 2.5D IC Packaging Product and Services
 - 2.12.4 JCET 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)
 - 2.12.5 JCET Recent Developments/Updates
- 2.13 TongFu Microelectronics
 - 2.13.1 TongFu Microelectronics Details
 - 2.13.2 TongFu Microelectronics Major Business
 - 2.13.3 TongFu Microelectronics 3D IC & 2.5D IC Packaging Product and Services

2.13.4 TongFu Microelectronics 3D IC & 2.5D IC Packaging Sales Quantity, Average Price, Revenue, Gross Margin and Market Share (2019-2024)

2.13.5 TongFu Microelectronics Recent Developments/Updates

3 COMPETITIVE ENVIRONMENT: 3D IC & 2.5D IC PACKAGING BY MANUFACTURER

3.1 Global 3D IC & 2.5D IC Packaging Sales Quantity by Manufacturer (2019-2024)

3.2 Global 3D IC & 2.5D IC Packaging Revenue by Manufacturer (2019-2024)

3.3 Global 3D IC & 2.5D IC Packaging Average Price by Manufacturer (2019-2024)

3.4 Market Share Analysis (2023)

3.4.1 Producer Shipments of 3D IC & 2.5D IC Packaging by Manufacturer Revenue (\$MM) and Market Share (%): 2023

3.4.2 Top 3 3D IC & 2.5D IC Packaging Manufacturer Market Share in 2023

3.4.2 Top 6 3D IC & 2.5D IC Packaging Manufacturer Market Share in 2023

3.5 3D IC & 2.5D IC Packaging Market: Overall Company Footprint Analysis

3.5.1 3D IC & 2.5D IC Packaging Market: Region Footprint

3.5.2 3D IC & 2.5D IC Packaging Market: Company Product Type Footprint

3.5.3 3D IC & 2.5D IC Packaging Market: Company Product Application Footprint

3.6 New Market Entrants and Barriers to Market Entry

3.7 Mergers, Acquisition, Agreements, and Collaborations

4 CONSUMPTION ANALYSIS BY REGION

4.1 Global 3D IC & 2.5D IC Packaging Market Size by Region

4.1.1 Global 3D IC & 2.5D IC Packaging Sales Quantity by Region (2019-2030)

4.1.2 Global 3D IC & 2.5D IC Packaging Consumption Value by Region (2019-2030)

4.1.3 Global 3D IC & 2.5D IC Packaging Average Price by Region (2019-2030)

4.2 North America 3D IC & 2.5D IC Packaging Consumption Value (2019-2030)

4.3 Europe 3D IC & 2.5D IC Packaging Consumption Value (2019-2030)

4.4 Asia-Pacific 3D IC & 2.5D IC Packaging Consumption Value (2019-2030)

4.5 South America 3D IC & 2.5D IC Packaging Consumption Value (2019-2030)

4.6 Middle East and Africa 3D IC & 2.5D IC Packaging Consumption Value (2019-2030)

5 MARKET SEGMENT BY TYPE

5.1 Global 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2030)

5.2 Global 3D IC & 2.5D IC Packaging Consumption Value by Type (2019-2030)

5.3 Global 3D IC & 2.5D IC Packaging Average Price by Type (2019-2030)

6 MARKET SEGMENT BY APPLICATION

6.1 Global 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2030)

6.2 Global 3D IC & 2.5D IC Packaging Consumption Value by Application (2019-2030)

6.3 Global 3D IC & 2.5D IC Packaging Average Price by Application (2019-2030)

7 NORTH AMERICA

7.1 North America 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2030)

7.2 North America 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2030)

7.3 North America 3D IC & 2.5D IC Packaging Market Size by Country

7.3.1 North America 3D IC & 2.5D IC Packaging Sales Quantity by Country (2019-2030)

7.3.2 North America 3D IC & 2.5D IC Packaging Consumption Value by Country (2019-2030)

7.3.3 United States Market Size and Forecast (2019-2030)

7.3.4 Canada Market Size and Forecast (2019-2030)

7.3.5 Mexico Market Size and Forecast (2019-2030)

8 EUROPE

8.1 Europe 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2030)

8.2 Europe 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2030)

8.3 Europe 3D IC & 2.5D IC Packaging Market Size by Country

8.3.1 Europe 3D IC & 2.5D IC Packaging Sales Quantity by Country (2019-2030)

8.3.2 Europe 3D IC & 2.5D IC Packaging Consumption Value by Country (2019-2030)

8.3.3 Germany Market Size and Forecast (2019-2030)

8.3.4 France Market Size and Forecast (2019-2030)

8.3.5 United Kingdom Market Size and Forecast (2019-2030)

8.3.6 Russia Market Size and Forecast (2019-2030)

8.3.7 Italy Market Size and Forecast (2019-2030)

9 ASIA-PACIFIC

9.1 Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2030)

9.2 Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2030)

9.3 Asia-Pacific 3D IC & 2.5D IC Packaging Market Size by Region

- 9.3.1 Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity by Region (2019-2030)
- 9.3.2 Asia-Pacific 3D IC & 2.5D IC Packaging Consumption Value by Region (2019-2030)
- 9.3.3 China Market Size and Forecast (2019-2030)
- 9.3.4 Japan Market Size and Forecast (2019-2030)
- 9.3.5 Korea Market Size and Forecast (2019-2030)
- 9.3.6 India Market Size and Forecast (2019-2030)
- 9.3.7 Southeast Asia Market Size and Forecast (2019-2030)
- 9.3.8 Australia Market Size and Forecast (2019-2030)

10 SOUTH AMERICA

- 10.1 South America 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2030)
- 10.2 South America 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2030)
- 10.3 South America 3D IC & 2.5D IC Packaging Market Size by Country
 - 10.3.1 South America 3D IC & 2.5D IC Packaging Sales Quantity by Country (2019-2030)
 - 10.3.2 South America 3D IC & 2.5D IC Packaging Consumption Value by Country (2019-2030)
 - 10.3.3 Brazil Market Size and Forecast (2019-2030)
 - 10.3.4 Argentina Market Size and Forecast (2019-2030)

11 MIDDLE EAST & AFRICA

- 11.1 Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2030)
- 11.2 Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2030)
- 11.3 Middle East & Africa 3D IC & 2.5D IC Packaging Market Size by Country
 - 11.3.1 Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity by Country (2019-2030)
 - 11.3.2 Middle East & Africa 3D IC & 2.5D IC Packaging Consumption Value by Country (2019-2030)
 - 11.3.3 Turkey Market Size and Forecast (2019-2030)
 - 11.3.4 Egypt Market Size and Forecast (2019-2030)
 - 11.3.5 Saudi Arabia Market Size and Forecast (2019-2030)
 - 11.3.6 South Africa Market Size and Forecast (2019-2030)

12 MARKET DYNAMICS

- 12.1 3D IC & 2.5D IC Packaging Market Drivers
- 12.2 3D IC & 2.5D IC Packaging Market Restraints
- 12.3 3D IC & 2.5D IC Packaging Trends Analysis
- 12.4 Porters Five Forces Analysis
 - 12.4.1 Threat of New Entrants
 - 12.4.2 Bargaining Power of Suppliers
 - 12.4.3 Bargaining Power of Buyers
 - 12.4.4 Threat of Substitutes
 - 12.4.5 Competitive Rivalry

13 RAW MATERIAL AND INDUSTRY CHAIN

- 13.1 Raw Material of 3D IC & 2.5D IC Packaging and Key Manufacturers
- 13.2 Manufacturing Costs Percentage of 3D IC & 2.5D IC Packaging
- 13.3 3D IC & 2.5D IC Packaging Production Process
- 13.4 3D IC & 2.5D IC Packaging Industrial Chain

14 SHIPMENTS BY DISTRIBUTION CHANNEL

- 14.1 Sales Channel
 - 14.1.1 Direct to End-User
 - 14.1.2 Distributors
- 14.2 3D IC & 2.5D IC Packaging Typical Distributors
- 14.3 3D IC & 2.5D IC Packaging Typical Customers

15 RESEARCH FINDINGS AND CONCLUSION

16 APPENDIX

- 16.1 Methodology
- 16.2 Research Process and Data Source
- 16.3 Disclaimer

List Of Tables

LIST OF TABLES

Table 1. Global 3D IC & 2.5D IC Packaging Consumption Value by Type, (USD Million), 2019 & 2023 & 2030

Table 2. Global 3D IC & 2.5D IC Packaging Consumption Value by Application, (USD Million), 2019 & 2023 & 2030

Table 3. Intel Corporation Basic Information, Manufacturing Base and Competitors

Table 4. Intel Corporation Major Business

Table 5. Intel Corporation 3D IC & 2.5D IC Packaging Product and Services

Table 6. Intel Corporation 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 7. Intel Corporation Recent Developments/Updates

Table 8. Toshiba Corp Basic Information, Manufacturing Base and Competitors

Table 9. Toshiba Corp Major Business

Table 10. Toshiba Corp 3D IC & 2.5D IC Packaging Product and Services

Table 11. Toshiba Corp 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 12. Toshiba Corp Recent Developments/Updates

Table 13. Samsung Electronics Basic Information, Manufacturing Base and Competitors

Table 14. Samsung Electronics Major Business

Table 15. Samsung Electronics 3D IC & 2.5D IC Packaging Product and Services

Table 16. Samsung Electronics 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 17. Samsung Electronics Recent Developments/Updates

Table 18. Stmicroelectronics Basic Information, Manufacturing Base and Competitors

Table 19. Stmicroelectronics Major Business

Table 20. Stmicroelectronics 3D IC & 2.5D IC Packaging Product and Services

Table 21. Stmicroelectronics 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 22. Stmicroelectronics Recent Developments/Updates

Table 23. Taiwan Semiconductor Manufacturing Basic Information, Manufacturing Base and Competitors

Table 24. Taiwan Semiconductor Manufacturing Major Business

Table 25. Taiwan Semiconductor Manufacturing 3D IC & 2.5D IC Packaging Product and Services

Table 26. Taiwan Semiconductor Manufacturing 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 27. Taiwan Semiconductor Manufacturing Recent Developments/Updates

Table 28. Amkor Technology Basic Information, Manufacturing Base and Competitors

Table 29. Amkor Technology Major Business

Table 30. Amkor Technology 3D IC & 2.5D IC Packaging Product and Services

Table 31. Amkor Technology 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 32. Amkor Technology Recent Developments/Updates

Table 33. United Microelectronics Basic Information, Manufacturing Base and Competitors

Table 34. United Microelectronics Major Business

Table 35. United Microelectronics 3D IC & 2.5D IC Packaging Product and Services

Table 36. United Microelectronics 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 37. United Microelectronics Recent Developments/Updates

Table 38. Broadcom Basic Information, Manufacturing Base and Competitors

Table 39. Broadcom Major Business

Table 40. Broadcom 3D IC & 2.5D IC Packaging Product and Services

Table 41. Broadcom 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 42. Broadcom Recent Developments/Updates

Table 43. ASE Group Basic Information, Manufacturing Base and Competitors

Table 44. ASE Group Major Business

Table 45. ASE Group 3D IC & 2.5D IC Packaging Product and Services

Table 46. ASE Group 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 47. ASE Group Recent Developments/Updates

Table 48. Pure Storage Basic Information, Manufacturing Base and Competitors

Table 49. Pure Storage Major Business

Table 50. Pure Storage 3D IC & 2.5D IC Packaging Product and Services

Table 51. Pure Storage 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)

Table 52. Pure Storage Recent Developments/Updates

Table 53. Advanced Semiconductor Engineering Basic Information, Manufacturing Base and Competitors

- Table 54. Advanced Semiconductor Engineering Major Business
- Table 55. Advanced Semiconductor Engineering 3D IC & 2.5D IC Packaging Product and Services
- Table 56. Advanced Semiconductor Engineering 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)
- Table 57. Advanced Semiconductor Engineering Recent Developments/Updates
- Table 58. JCET Basic Information, Manufacturing Base and Competitors
- Table 59. JCET Major Business
- Table 60. JCET 3D IC & 2.5D IC Packaging Product and Services
- Table 61. JCET 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)
- Table 62. JCET Recent Developments/Updates
- Table 63. TongFu Microelectronics Basic Information, Manufacturing Base and Competitors
- Table 64. TongFu Microelectronics Major Business
- Table 65. TongFu Microelectronics 3D IC & 2.5D IC Packaging Product and Services
- Table 66. TongFu Microelectronics 3D IC & 2.5D IC Packaging Sales Quantity (K Units), Average Price (USD/Unit), Revenue (USD Million), Gross Margin and Market Share (2019-2024)
- Table 67. TongFu Microelectronics Recent Developments/Updates
- Table 68. Global 3D IC & 2.5D IC Packaging Sales Quantity by Manufacturer (2019-2024) & (K Units)
- Table 69. Global 3D IC & 2.5D IC Packaging Revenue by Manufacturer (2019-2024) & (USD Million)
- Table 70. Global 3D IC & 2.5D IC Packaging Average Price by Manufacturer (2019-2024) & (USD/Unit)
- Table 71. Market Position of Manufacturers in 3D IC & 2.5D IC Packaging, (Tier 1, Tier 2, and Tier 3), Based on Consumption Value in 2023
- Table 72. Head Office and 3D IC & 2.5D IC Packaging Production Site of Key Manufacturer
- Table 73. 3D IC & 2.5D IC Packaging Market: Company Product Type Footprint
- Table 74. 3D IC & 2.5D IC Packaging Market: Company Product Application Footprint
- Table 75. 3D IC & 2.5D IC Packaging New Market Entrants and Barriers to Market Entry
- Table 76. 3D IC & 2.5D IC Packaging Mergers, Acquisition, Agreements, and Collaborations
- Table 77. Global 3D IC & 2.5D IC Packaging Sales Quantity by Region (2019-2024) & (K Units)
- Table 78. Global 3D IC & 2.5D IC Packaging Sales Quantity by Region (2025-2030) &

(K Units)

Table 79. Global 3D IC & 2.5D IC Packaging Consumption Value by Region (2019-2024) & (USD Million)

Table 80. Global 3D IC & 2.5D IC Packaging Consumption Value by Region (2025-2030) & (USD Million)

Table 81. Global 3D IC & 2.5D IC Packaging Average Price by Region (2019-2024) & (USD/Unit)

Table 82. Global 3D IC & 2.5D IC Packaging Average Price by Region (2025-2030) & (USD/Unit)

Table 83. Global 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2024) & (K Units)

Table 84. Global 3D IC & 2.5D IC Packaging Sales Quantity by Type (2025-2030) & (K Units)

Table 85. Global 3D IC & 2.5D IC Packaging Consumption Value by Type (2019-2024) & (USD Million)

Table 86. Global 3D IC & 2.5D IC Packaging Consumption Value by Type (2025-2030) & (USD Million)

Table 87. Global 3D IC & 2.5D IC Packaging Average Price by Type (2019-2024) & (USD/Unit)

Table 88. Global 3D IC & 2.5D IC Packaging Average Price by Type (2025-2030) & (USD/Unit)

Table 89. Global 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2024) & (K Units)

Table 90. Global 3D IC & 2.5D IC Packaging Sales Quantity by Application (2025-2030) & (K Units)

Table 91. Global 3D IC & 2.5D IC Packaging Consumption Value by Application (2019-2024) & (USD Million)

Table 92. Global 3D IC & 2.5D IC Packaging Consumption Value by Application (2025-2030) & (USD Million)

Table 93. Global 3D IC & 2.5D IC Packaging Average Price by Application (2019-2024) & (USD/Unit)

Table 94. Global 3D IC & 2.5D IC Packaging Average Price by Application (2025-2030) & (USD/Unit)

Table 95. North America 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2024) & (K Units)

Table 96. North America 3D IC & 2.5D IC Packaging Sales Quantity by Type (2025-2030) & (K Units)

Table 97. North America 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2024) & (K Units)

Table 98. North America 3D IC & 2.5D IC Packaging Sales Quantity by Application (2025-2030) & (K Units)

Table 99. North America 3D IC & 2.5D IC Packaging Sales Quantity by Country (2019-2024) & (K Units)

Table 100. North America 3D IC & 2.5D IC Packaging Sales Quantity by Country (2025-2030) & (K Units)

Table 101. North America 3D IC & 2.5D IC Packaging Consumption Value by Country (2019-2024) & (USD Million)

Table 102. North America 3D IC & 2.5D IC Packaging Consumption Value by Country (2025-2030) & (USD Million)

Table 103. Europe 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2024) & (K Units)

Table 104. Europe 3D IC & 2.5D IC Packaging Sales Quantity by Type (2025-2030) & (K Units)

Table 105. Europe 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2024) & (K Units)

Table 106. Europe 3D IC & 2.5D IC Packaging Sales Quantity by Application (2025-2030) & (K Units)

Table 107. Europe 3D IC & 2.5D IC Packaging Sales Quantity by Country (2019-2024) & (K Units)

Table 108. Europe 3D IC & 2.5D IC Packaging Sales Quantity by Country (2025-2030) & (K Units)

Table 109. Europe 3D IC & 2.5D IC Packaging Consumption Value by Country (2019-2024) & (USD Million)

Table 110. Europe 3D IC & 2.5D IC Packaging Consumption Value by Country (2025-2030) & (USD Million)

Table 111. Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2024) & (K Units)

Table 112. Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity by Type (2025-2030) & (K Units)

Table 113. Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2024) & (K Units)

Table 114. Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity by Application (2025-2030) & (K Units)

Table 115. Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity by Region (2019-2024) & (K Units)

Table 116. Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity by Region (2025-2030) & (K Units)

Table 117. Asia-Pacific 3D IC & 2.5D IC Packaging Consumption Value by Region

(2019-2024) & (USD Million)

Table 118. Asia-Pacific 3D IC & 2.5D IC Packaging Consumption Value by Region (2025-2030) & (USD Million)

Table 119. South America 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2024) & (K Units)

Table 120. South America 3D IC & 2.5D IC Packaging Sales Quantity by Type (2025-2030) & (K Units)

Table 121. South America 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2024) & (K Units)

Table 122. South America 3D IC & 2.5D IC Packaging Sales Quantity by Application (2025-2030) & (K Units)

Table 123. South America 3D IC & 2.5D IC Packaging Sales Quantity by Country (2019-2024) & (K Units)

Table 124. South America 3D IC & 2.5D IC Packaging Sales Quantity by Country (2025-2030) & (K Units)

Table 125. South America 3D IC & 2.5D IC Packaging Consumption Value by Country (2019-2024) & (USD Million)

Table 126. South America 3D IC & 2.5D IC Packaging Consumption Value by Country (2025-2030) & (USD Million)

Table 127. Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity by Type (2019-2024) & (K Units)

Table 128. Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity by Type (2025-2030) & (K Units)

Table 129. Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity by Application (2019-2024) & (K Units)

Table 130. Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity by Application (2025-2030) & (K Units)

Table 131. Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity by Region (2019-2024) & (K Units)

Table 132. Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity by Region (2025-2030) & (K Units)

Table 133. Middle East & Africa 3D IC & 2.5D IC Packaging Consumption Value by Region (2019-2024) & (USD Million)

Table 134. Middle East & Africa 3D IC & 2.5D IC Packaging Consumption Value by Region (2025-2030) & (USD Million)

Table 135. 3D IC & 2.5D IC Packaging Raw Material

Table 136. Key Manufacturers of 3D IC & 2.5D IC Packaging Raw Materials

Table 137. 3D IC & 2.5D IC Packaging Typical Distributors

Table 138. 3D IC & 2.5D IC Packaging Typical Customers

List Of Figures

LIST OF FIGURES

Figure 1. 3D IC & 2.5D IC Packaging Picture

Figure 2. Global 3D IC & 2.5D IC Packaging Consumption Value by Type, (USD Million), 2019 & 2023 & 2030

Figure 3. Global 3D IC & 2.5D IC Packaging Consumption Value Market Share by Type in 2023

Figure 4. 3D TSV Examples

Figure 5. 2.5D and 3D Wafer-Level Chip-Scale Packaging (WLCSP) Examples

Figure 6. Global 3D IC & 2.5D IC Packaging Consumption Value by Application, (USD Million), 2019 & 2023 & 2030

Figure 7. Global 3D IC & 2.5D IC Packaging Consumption Value Market Share by Application in 2023

Figure 8. Automotive Examples

Figure 9. Consumer electronics Examples

Figure 10. Medical devices Examples

Figure 11. Military & aerospace Examples

Figure 12. Telecommunication Examples

Figure 13. Industrial sector and smart technologies Examples

Figure 14. Global 3D IC & 2.5D IC Packaging Consumption Value, (USD Million): 2019 & 2023 & 2030

Figure 15. Global 3D IC & 2.5D IC Packaging Consumption Value and Forecast (2019-2030) & (USD Million)

Figure 16. Global 3D IC & 2.5D IC Packaging Sales Quantity (2019-2030) & (K Units)

Figure 17. Global 3D IC & 2.5D IC Packaging Average Price (2019-2030) & (USD/Unit)

Figure 18. Global 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Manufacturer in 2023

Figure 19. Global 3D IC & 2.5D IC Packaging Consumption Value Market Share by Manufacturer in 2023

Figure 20. Producer Shipments of 3D IC & 2.5D IC Packaging by Manufacturer Sales Quantity (\$MM) and Market Share (%): 2023

Figure 21. Top 3 3D IC & 2.5D IC Packaging Manufacturer (Consumption Value) Market Share in 2023

Figure 22. Top 6 3D IC & 2.5D IC Packaging Manufacturer (Consumption Value) Market Share in 2023

Figure 23. Global 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Region (2019-2030)

Figure 24. Global 3D IC & 2.5D IC Packaging Consumption Value Market Share by Region (2019-2030)

Figure 25. North America 3D IC & 2.5D IC Packaging Consumption Value (2019-2030) & (USD Million)

Figure 26. Europe 3D IC & 2.5D IC Packaging Consumption Value (2019-2030) & (USD Million)

Figure 27. Asia-Pacific 3D IC & 2.5D IC Packaging Consumption Value (2019-2030) & (USD Million)

Figure 28. South America 3D IC & 2.5D IC Packaging Consumption Value (2019-2030) & (USD Million)

Figure 29. Middle East & Africa 3D IC & 2.5D IC Packaging Consumption Value (2019-2030) & (USD Million)

Figure 30. Global 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Type (2019-2030)

Figure 31. Global 3D IC & 2.5D IC Packaging Consumption Value Market Share by Type (2019-2030)

Figure 32. Global 3D IC & 2.5D IC Packaging Average Price by Type (2019-2030) & (USD/Unit)

Figure 33. Global 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Application (2019-2030)

Figure 34. Global 3D IC & 2.5D IC Packaging Consumption Value Market Share by Application (2019-2030)

Figure 35. Global 3D IC & 2.5D IC Packaging Average Price by Application (2019-2030) & (USD/Unit)

Figure 36. North America 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Type (2019-2030)

Figure 37. North America 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Application (2019-2030)

Figure 38. North America 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Country (2019-2030)

Figure 39. North America 3D IC & 2.5D IC Packaging Consumption Value Market Share by Country (2019-2030)

Figure 40. United States 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 41. Canada 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 42. Mexico 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 43. Europe 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Type

(2019-2030)

Figure 44. Europe 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Application (2019-2030)

Figure 45. Europe 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Country (2019-2030)

Figure 46. Europe 3D IC & 2.5D IC Packaging Consumption Value Market Share by Country (2019-2030)

Figure 47. Germany 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 48. France 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 49. United Kingdom 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 50. Russia 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 51. Italy 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 52. Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Type (2019-2030)

Figure 53. Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Application (2019-2030)

Figure 54. Asia-Pacific 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Region (2019-2030)

Figure 55. Asia-Pacific 3D IC & 2.5D IC Packaging Consumption Value Market Share by Region (2019-2030)

Figure 56. China 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 57. Japan 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 58. Korea 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 59. India 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 60. Southeast Asia 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 61. Australia 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)

Figure 62. South America 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Type (2019-2030)

- Figure 63. South America 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Application (2019-2030)
- Figure 64. South America 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Country (2019-2030)
- Figure 65. South America 3D IC & 2.5D IC Packaging Consumption Value Market Share by Country (2019-2030)
- Figure 66. Brazil 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)
- Figure 67. Argentina 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)
- Figure 68. Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Type (2019-2030)
- Figure 69. Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Application (2019-2030)
- Figure 70. Middle East & Africa 3D IC & 2.5D IC Packaging Sales Quantity Market Share by Region (2019-2030)
- Figure 71. Middle East & Africa 3D IC & 2.5D IC Packaging Consumption Value Market Share by Region (2019-2030)
- Figure 72. Turkey 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)
- Figure 73. Egypt 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)
- Figure 74. Saudi Arabia 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)
- Figure 75. South Africa 3D IC & 2.5D IC Packaging Consumption Value and Growth Rate (2019-2030) & (USD Million)
- Figure 76. 3D IC & 2.5D IC Packaging Market Drivers
- Figure 77. 3D IC & 2.5D IC Packaging Market Restraints
- Figure 78. 3D IC & 2.5D IC Packaging Market Trends
- Figure 79. Porters Five Forces Analysis
- Figure 80. Manufacturing Cost Structure Analysis of 3D IC & 2.5D IC Packaging in 2023
- Figure 81. Manufacturing Process Analysis of 3D IC & 2.5D IC Packaging
- Figure 82. 3D IC & 2.5D IC Packaging Industrial Chain
- Figure 83. Sales Quantity Channel: Direct to End-User vs Distributors
- Figure 84. Direct Channel Pros & Cons
- Figure 85. Indirect Channel Pros & Cons
- Figure 86. Methodology
- Figure 87. Research Process and Data Source

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